6th EUropean Failure Analysis NETwork EUFANET workshop

Failure Analysis of System in Package (SIP)

October 04, EUFANET Workshop at ESREF 2006

EUFANET Status Update

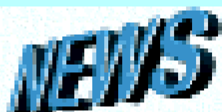
- 200 Members, 17 countries
- EUFANET kick off (2001)
- Email Forum (2002)
- Web site (2003)
  - FA Database (2005)
  - Yellowpages (2006)
- EUFANET legal status (2005)
- EUFANET board
  - definition (2006)
  - Election (2006)
- **EUFANET Workshop on Optical Localization Techniques** (2006, Postponed)

Yellow pages

EUropean Failure Analysis Network

EUFANET Info
Technical stuff
Workshops
Yellow pages
Workgroups
Contacts
Sitemap
Home

European FA Lab Yellow Pages



Yellow pages 2nd update. At this moment, it is just a list but it will move on to database as soon as the number of inputs exceed 100: more info

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Workshop program

16h10 Welcome and EUFANET status update
Philippe Perdu, CNES, Felix Beaudoin, CREDENCE, Christian Boit, TU Berlin

16h20 System in Package and Failure Analysis Challenges
Patrick Poirier, LaMIP/PHILIPS

16h50 Open Degradation on ITO Lines for an LCD Driver
Peter JACOB, EMPA

17h10 Evaluation of risks due to thermal stress before physical failure appearance
Michael Hertl, INSIDIX

17h40 Acoustic microscopy applied for SiP Physical analysis
Yves Ousten, Bruno Levrier, Jean Augereau, Laurent Bechou, IXL ENSEIRB

18h10 Addressing the Challenge of Backside Circuit Edit of Wafer Level Chip Scale Packages
Ted Lundquist, D. Di Donato, T Malik, CREDENCE

18h30 Localization of Electrical Shorts in Dies and Packages using Magnetic Microscopy and Lock-in Thermography
Andreas Altes, Martin Hechtl, INFINEON

19h00 Magnetic Current Imaging to “see through” System in Package Devices
Lee Knauss, NEOCERA

19h30 Closing remarks